

Thin Film, High-Density Interconnects



KEY BENEFITS

- Enhanced signal routing
- Size integration
- Improved response conditioning
- Low noise < - 30 dB

APPLICATIONS

- Microwave circuitry
- High-performance, low-noise power amplifiers
- Avionics
- Satellites

RESOURCES

- Datasheet: HDI - <http://www.vishay.com/doc?61058>
- For technical questions contact efi@vishay.com



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Standard Layout Guidelines

DESIGN CAPABILITIES

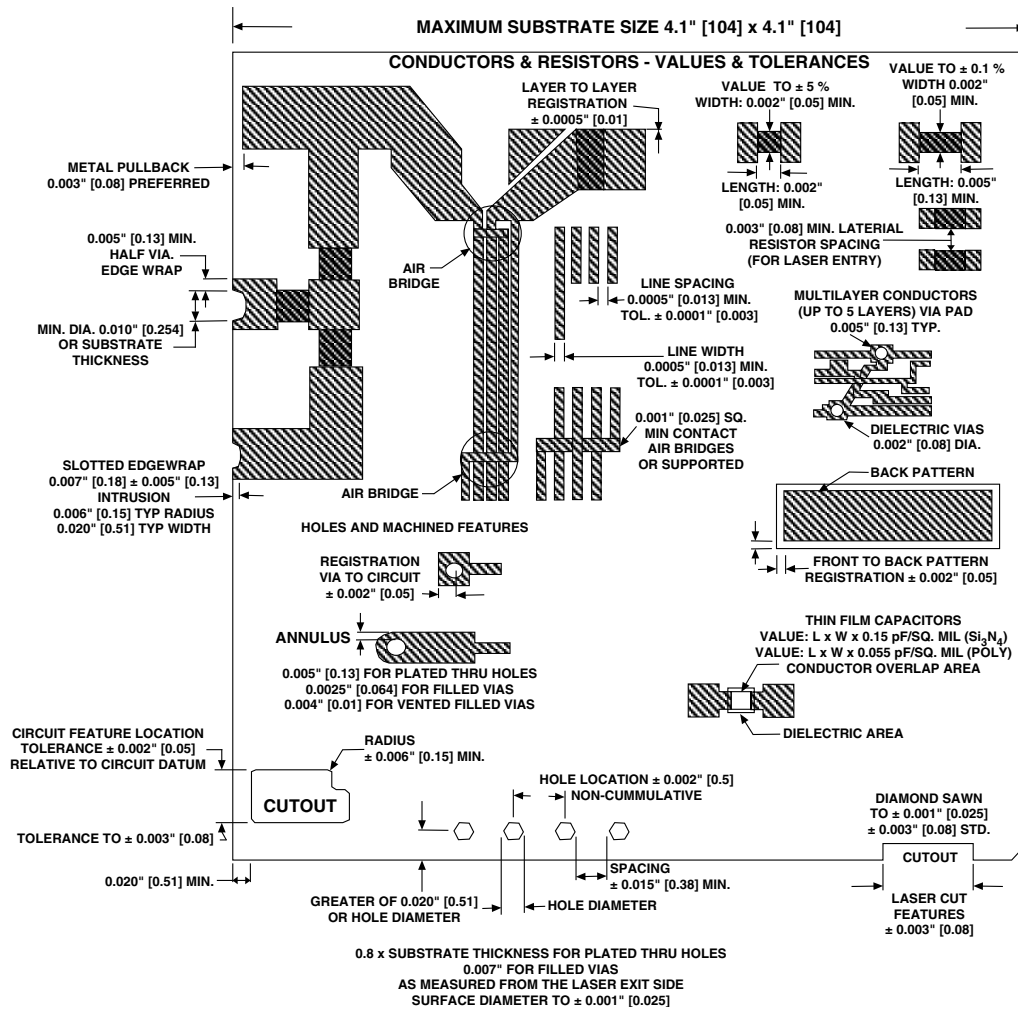
Thin Film High Density Interconnect design guide is directed at engineers looking to design the following:

- Simple resistor networks
- Integrated resistor-capacitor networks
- Multilayer substrate that involve up to 5 layers
- Custom thin film substrate on alumina (Al₂O₃) Aluminum nitride (AlN) or beryllium oxide (BeO)
- Substrates with special shapes, vias, and patterns
- Substrates for microwave applications

The wide array of capabilities allows users to find solutions for applications servicing many markets such as:

- Military
- Automotive
- Instrumentation - microwave
- Telecommunications - CATV, fiber optic and wireless
- Aerospace
- Medical

DIMENSIONS in inches (millimeters)



Revision 09-Mar-07